

#2 / JDS
D. Deaton
11-21-01

Sheet 1 of 1

Form 1449*	Atty. Docket No.: 884.522US1	Serial No. Unknown
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Madhav Datta et al.	
	Filing Date: Herewith	Group: Unknown

U.S. PTO
09/961034
09/21/01

U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
--------------------	-----------------	------	------	-------	----------	----------------------------

FOREIGN PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes	No
--------------------	-----------------	------	---------	-------	----------	-----------------	----

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

**Examiner Initial	
LP	Annala, P., et al., "Electroplated Solder Alloys for Flip Chip Interconnections", <u>Physica Scripta</u> , T69, pp. 115-118, (1997)
I	Datta, M., et al., "Electrochemical Fabrication of Mechanically Robust PbSn C4 Interconnections", <u>Journal of the Electrochemical Society</u> , 142 (11), 7 p., (Nov. 1995)
I	Honma, S., et al., "Effectiveness of Thin-film Barrier Metals for Eutectic Solder Bumps", <u>Microelectronics International</u> , 14 (3), pp. 47-50, (Sept. 1997)
↓	Liu, C.Y., et al., "Electron microscopy study of interfacial reaction between eutectic SnPb and Cu/Ni(V)/Al thin film metallization", <u>Journal of Applied Physics</u> , 86 (11), pp. 1-5, (Dec. 1999)

Examiner

Long Pham

Date Considered

4/6/03

*Substitute Disclosure Statement Form (PTO-1449)

**EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.